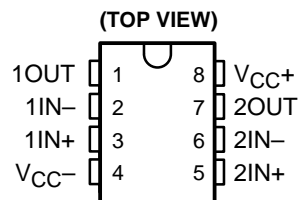


MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

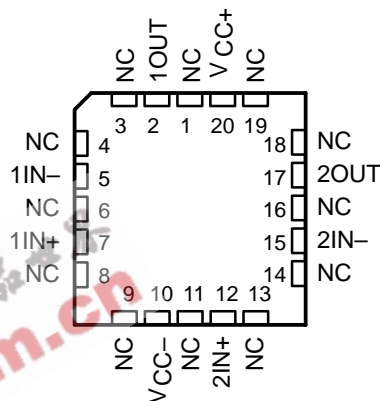
SLOS069B – FEBRUARY 1971 – REVISED SEPTEMBER 2002

- Short-Circuit Protection
- Wide Common-Mode and Differential Voltage Ranges
- No Frequency Compensation Required
- Low Power Consumption
- No Latch-Up
- Designed to Be Interchangeable With Motorola MC1558/MC1458 and Signetics S5558/N5558

MC1458 . . . D, P, OR PS PACKAGE
MC1558 . . . JG PACKAGE



MC1558 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description/ordering information

The MC1458 and MC1558 are dual general-purpose operational amplifiers, with each half electrically similar to the μ A741, except that offset null capability is not provided.

The high-common-mode input voltage range and the absence of latch-up make these amplifiers ideal for voltage-follower applications. The devices are short-circuit protected and the internal frequency compensation ensures stability without external components.

ORDERING INFORMATION

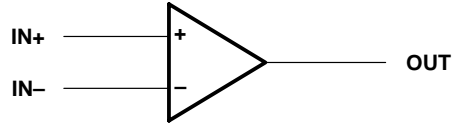
TA	V _{IO} max AT 25°C	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	6 mV	PDIP (P)	Tube	MC1458P	MC1458P
		SOIC (D)	Tube	MC1458D	MC1458
			Tape and reel	MC1458DR	
		SOP (PS)	Tape and reel	MC1458PSR	M1458
–55°C to 125°C	5 mV	CDIP (JG)	Tube	MC1558JG	MC1558JG
		CDIP (JGB)	Tube	MC1558JGB	MC1558JGB
		LCCC (FK)	Tube	MC1558FK	MC1558FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

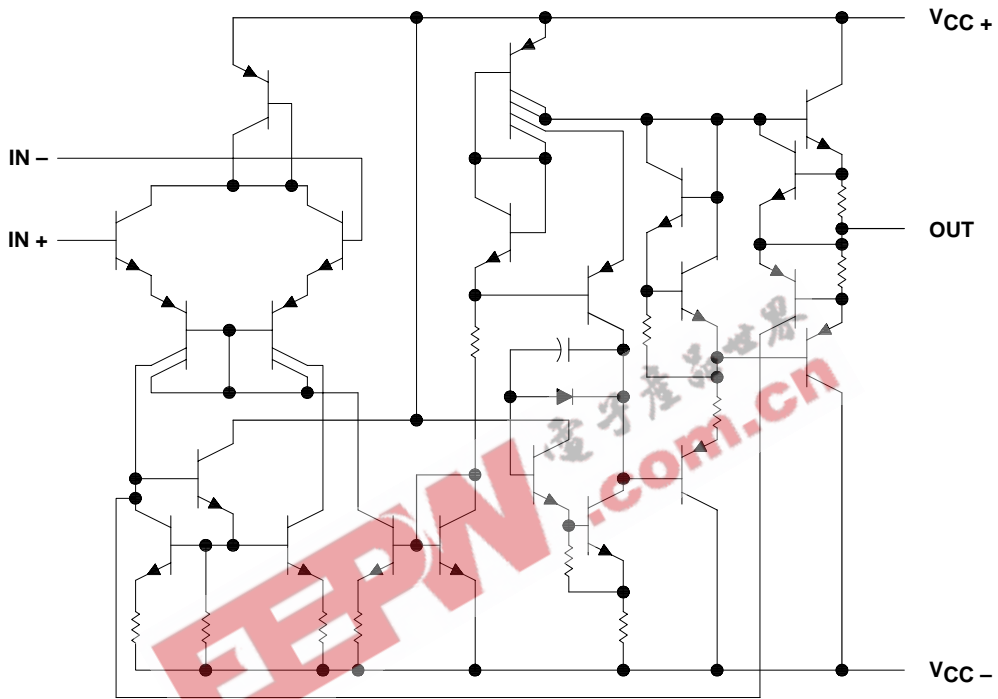
MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069B – FEBRUARY 1971 – REVISED SEPTEMBER 2002

symbol (each amplifier)



schematic (each amplifier)



MC1458, MC1558

DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069B – FEBRUARY 1971 – REVISED SEPTEMBER 2002

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC+} (see Note 1):	MC1458	18 V
	MC1558	22 V
Supply voltage, V_{CC-} (see Note 1):	MC1458	–18 V
	MC1558	–22 V
Differential input voltage, V_{ID} (see Note 2)		±30 V
Input voltage, V_I (either input, see Notes 1 and 3)		±15 V
Duration of output short circuit (see Note 4)		Unlimited
Operating virtual junction temperature, T_J		150°C
Package thermal impedance, θ_{JA} (see Notes 5 and 6):	D package	97°C/W
	P package	85°C/W
	PS package	95°C/W
Package thermal impedance, θ_{JC} (see Notes 7 and 8):	FK package	5.61°C/W
	JG package	14.5°C/W
Case temperature for 60 seconds: FK package		260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: JG package		300°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: D, P, or PS package		260°C
Storage temperature range, T_{stg}		–65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. All voltage values, unless otherwise noted, are with respect to the midpoint between V_{CC+} and V_{CC-} .
 2. Differential voltages are at $IN+$ with respect to $IN-$.
 3. The magnitude of the input voltage must never exceed the magnitude of the supply voltage or 15 V, whichever is less.
 4. The output can be shorted to ground or either power supply. For the MC1558 only, the unlimited duration of the short circuit applies at (or below) 125°C case temperature or 70°C free-air temperature.
 5. Maximum power dissipation is a function of $T_J(max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 6. The package thermal impedance is calculated in accordance with JESD 51-7.
 7. Maximum power dissipation is a function of $T_J(max)$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case temperature is $P_D = (T_J(max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.
 8. The package thermal impedance is calculated in accordance with MIL-STD-883.

recommended operating conditions

		MIN	MAX	UNIT
$V_{CC\pm}$	Supply voltage	±5	±15	V
T_A	Operating free-air temperature range	MC1458	0 70	°C
		MC1558	–55 125	

MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069B – FEBRUARY 1971 – REVISED SEPTEMBER 2002

electrical characteristics at specified free-air temperature, $V_{CC\pm} = \pm 15\text{ V}$

PARAMETER	TEST CONDITIONS†	MC1458			MC1558			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
V_{IO} Input offset voltage	$V_O = 0$	25°C	1	6	1	5	mV	
		Full range		7.5		6		
I_{IO} Input offset current	$V_O = 0$	25°C	20	200	20	200	nA	
		Full range		300		500		
I_{IB} Input bias current	$V_O = 0$	25°C	80	500	80	500	nA	
		Full range		800		1500		
V_{ICR} Common-mode input voltage range		25°C	±12	±13	±12	±13	V	
		Full range	±12		±12			
V_{OM} Maximum peak output voltage swing	$R_L = 10\text{ k}\Omega$	25°C	±12	±14	±12	±14	V	
	$R_L \geq 10\text{ k}\Omega$	Full range	±12		±12			
	$R_L = 2\text{ k}\Omega$	25°C	±10	±13	±10	±13		
	$R_L \geq 2\text{ k}\Omega$	Full range	±10		±10			
A_{VD} Large-signal differential voltage amplification	$R_L \geq 2\text{ k}\Omega, V_O = \pm 10\text{ V}$	25°C	20	200	50	200	V/mV	
		Full range	15		25			
B_{OM} Maximum-output-swing bandwidth (closed loop)	$R_L = 2\text{ k}\Omega, A_{VD} = 1, THD \geq 5\%$	25°C		14		14	kHz	
B_1 Unity-gain bandwidth		25°C		1		1	MHz	
ϕ_m Phase margin	$A_{VD} = 1$	25°C		65		65	deg	
		Gain margin	25°C		11			11
r_i Input resistance		25°C	0.3	2	0.3*	2	M Ω	
r_o Output resistance	$V_O = 0, \text{ See Note 9}$	25°C		75		75	Ω	
C_i Input capacitance		25°C		1.4		1.4	pF	
z_{ic} Common-mode input impedance	$f = 20\text{ Hz}$	25°C		200		200	M Ω	
CMRR Common-mode rejection ratio	$V_{IC} = V_{ICR}\text{ min}, V_O = 0$	25°C	70	90	70	90	dB	
		Full range	70		70			
k_{SVS} Supply-voltage sensitivity ($\Delta V_{IO}/\Delta V_{CC}$)	$V_{CC} = \pm 9\text{ V to } \pm 15\text{ V}, V_O = 0$	25°C	30	150	30	150	$\mu\text{V/V}$	
		Full range		150		150		
V_n Equivalent input noise voltage (closed loop)	$A_{VD} = 100, R_S = 0, f = 1\text{ kHz}, BW = 1\text{ Hz}$	25°C		45		45	nV/ $\sqrt{\text{Hz}}$	
I_{OS} Short-circuit output current		25°C	±25	±40	±25	±40	mA	
I_{CC} Supply current (both amplifiers)	$V_O = 0, \text{ No load}$	25°C	3.4	5.6	3.4	5	mA	
		Full range		6.6		6.6		
P_D Total power dissipation (both amplifiers)	$V_O = 0, \text{ No load}$	25°C	100	170	100	150	mW	
		Full range		200		200		
V_{O1}/V_{O2} Crosstalk attenuation		25°C		120		120	dB	

*On products compliant to MIL-PRF-38535, this parameter is not production tested.

† All characteristics are specified under open-loop operating conditions with zero common-mode input voltage, unless otherwise specified. Full range for MC1458 is 0°C to 70°C and for MC1558 is -55°C to 125°C.

NOTE 9: This typical value applies only at frequencies above a few hundred hertz because of the effect of drift and thermal feedback.

MC1458, MC1558 DUAL GENERAL-PURPOSE OPERATIONAL AMPLIFIERS

SLOS069B – FEBRUARY 1971 – REVISED SEPTEMBER 2002

operating characteristics, $V_{CC\pm} = \pm 15\text{ V}$, $C_L = 100\text{ pF}$, $T_A = 25^\circ\text{C}$ (see Figure 1)

PARAMETER		TEST CONDITIONS		MC1458			MC1558			UNIT
				MIN	TYP	MAX	MIN	TYP	MAX	
t_r	Rise time	$V_I = 20\text{ mV}$,	$R_L = 2\text{ k}\Omega$,	0.3			0.3			μs
	Overshoot factor	$V_I = 20\text{ mV}$,	$R_L = 2\text{ k}\Omega$	5			5			%
SR	Slew rate at unity gain	$V_I = 10\text{ V}$,	$R_L = 2\text{ k}\Omega$	0.5			0.5			$\text{V}/\mu\text{s}$

PARAMETER MEASUREMENT INFORMATION

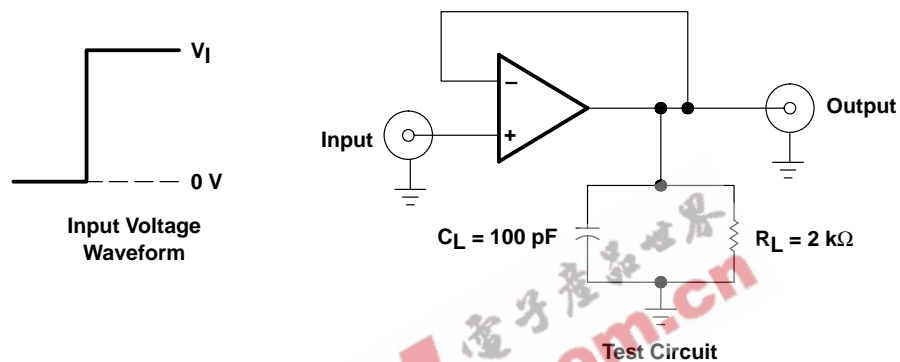


Figure 1. Rise-Time, Overshoot, and Slew-Rate Waveform and Test Circuit

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9760301Q2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9760301QPA	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
MC1458D	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC1458DE4	ACTIVE	SOIC	D	8	75	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC1458DR	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC1458DRE4	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC1458P	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MC1458PE4	ACTIVE	PDIP	P	8	50	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
MC1458PSR	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC1458PSRE4	ACTIVE	SO	PS	8	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
MC1558FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
MC1558JG	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
MC1558JGB	ACTIVE	CDIP	JG	8	1	TBD	A42 SNPB	N / A for Pkg Type
MC1558P	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI
SN98212P	OBSOLETE	PDIP	P	8		TBD	Call TI	Call TI

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

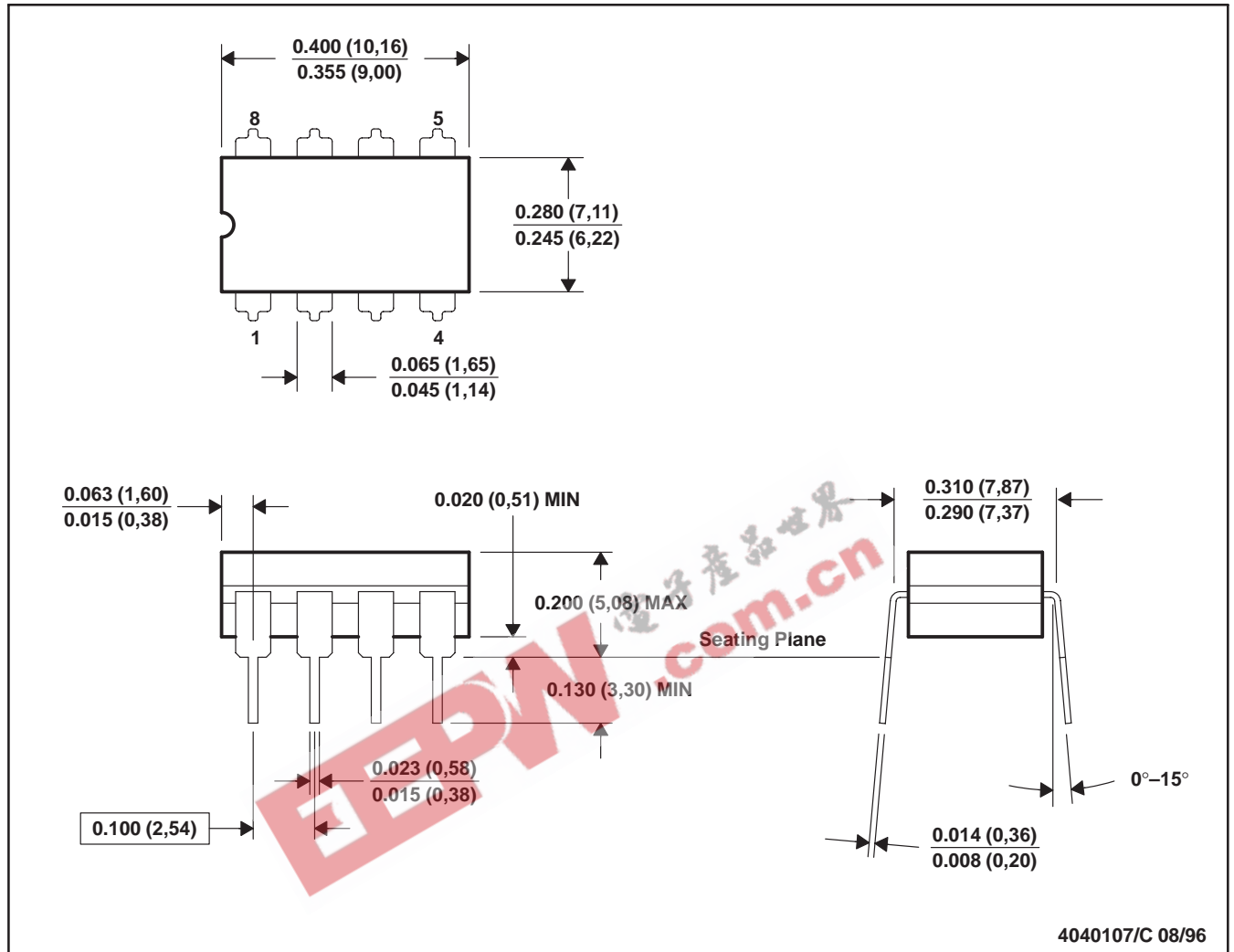
EEPW 电子產品世界
.com.cn

MECHANICAL DATA

MCER001A – JANUARY 1995 – REVISED JANUARY 1997

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE

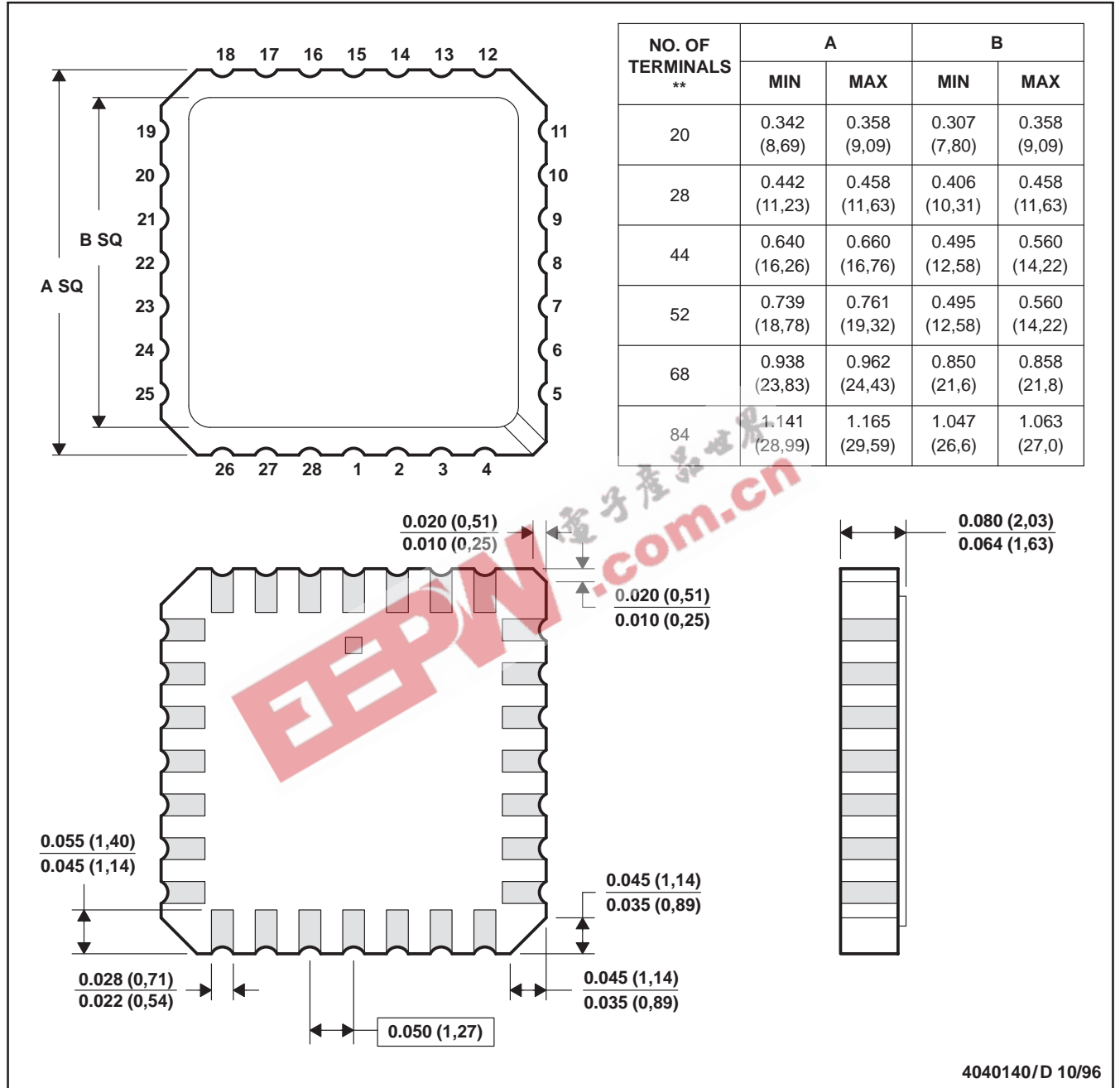


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification.
 - Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



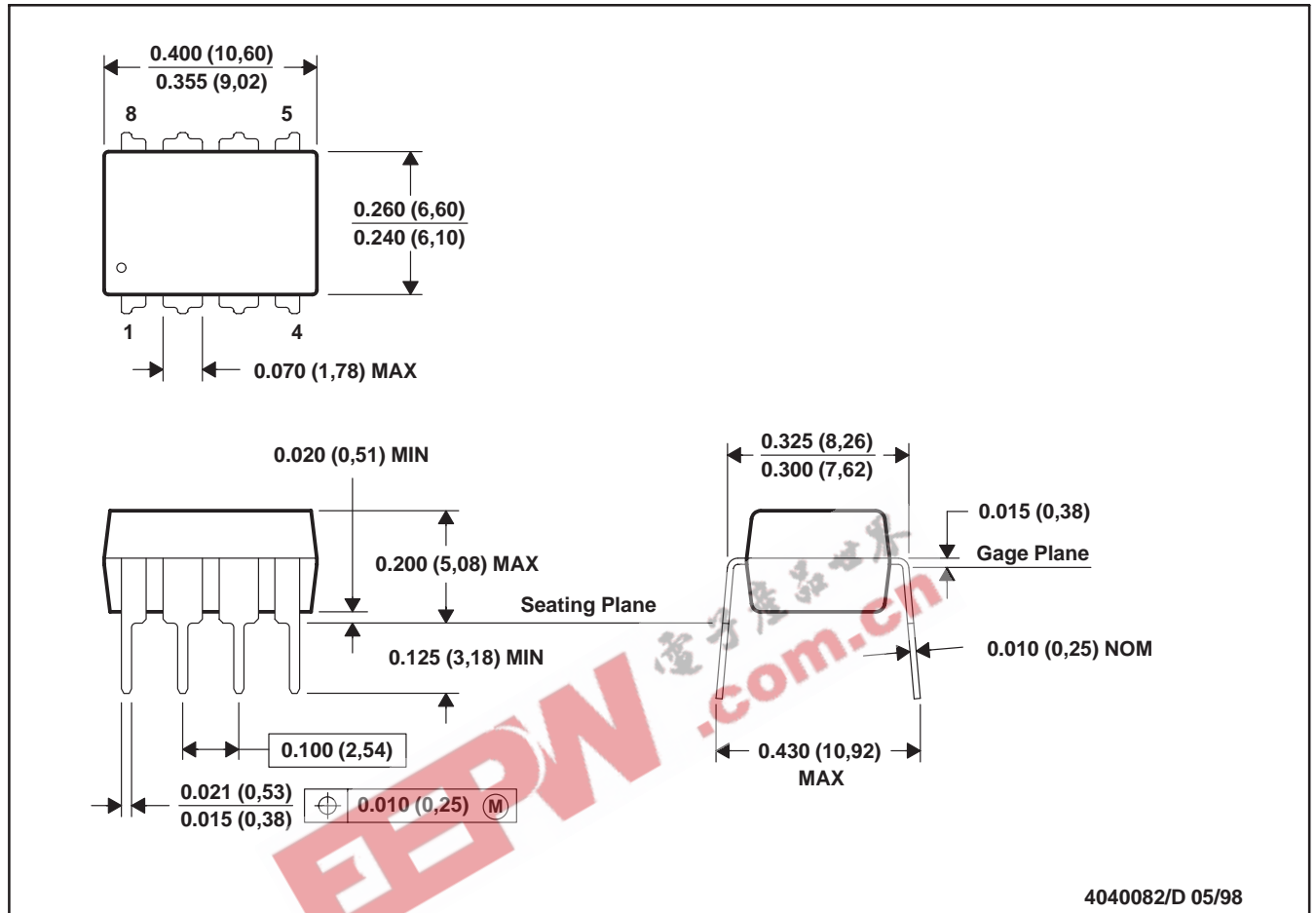
- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

MECHANICAL DATA

MPDI001A – JANUARY 1995 – REVISED JUNE 1999

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001

For the latest package information, go to http://www.ti.com/sc/docs/package/pkg_info.htm

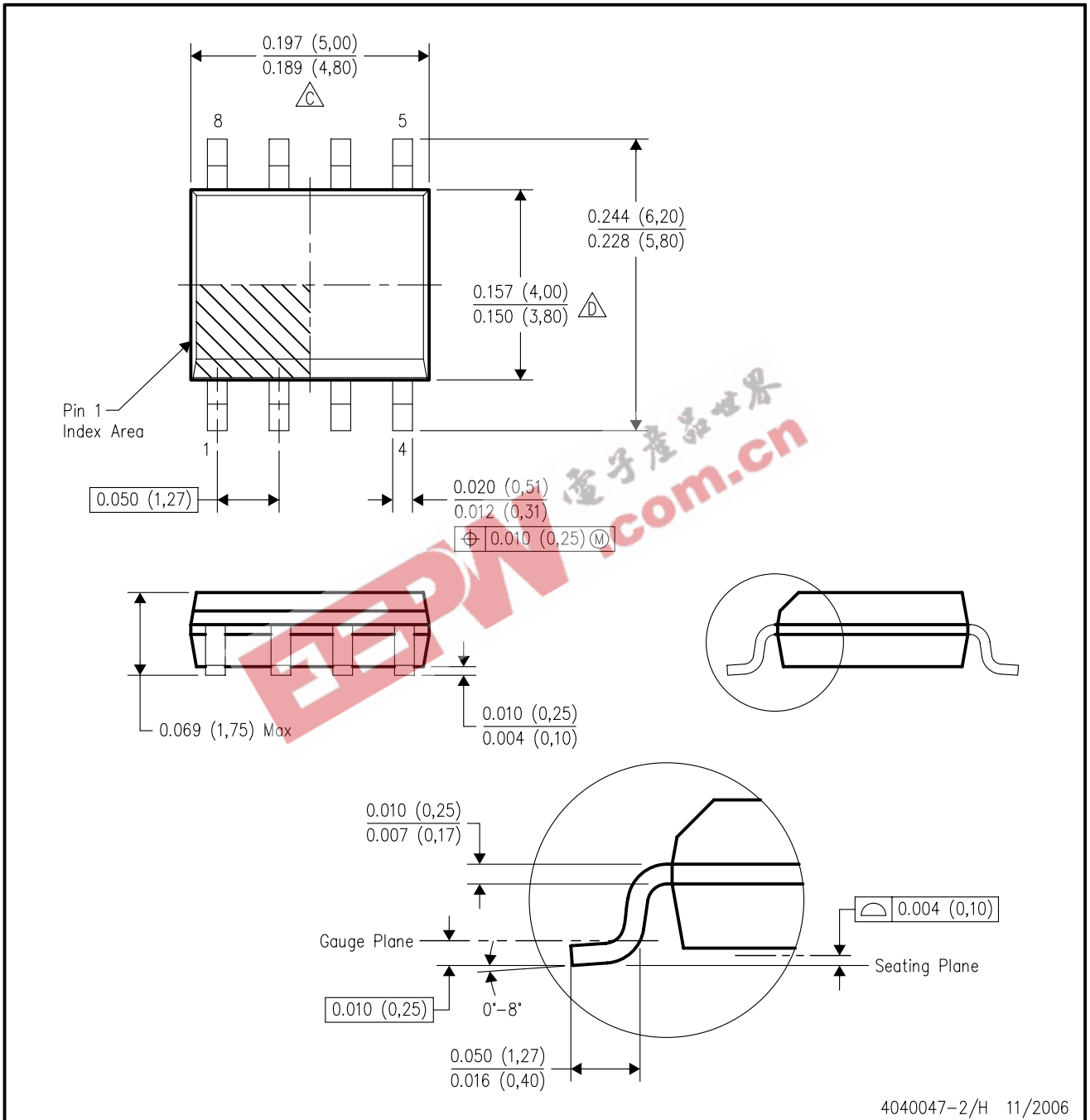


POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

MECHANICAL DATA

D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE

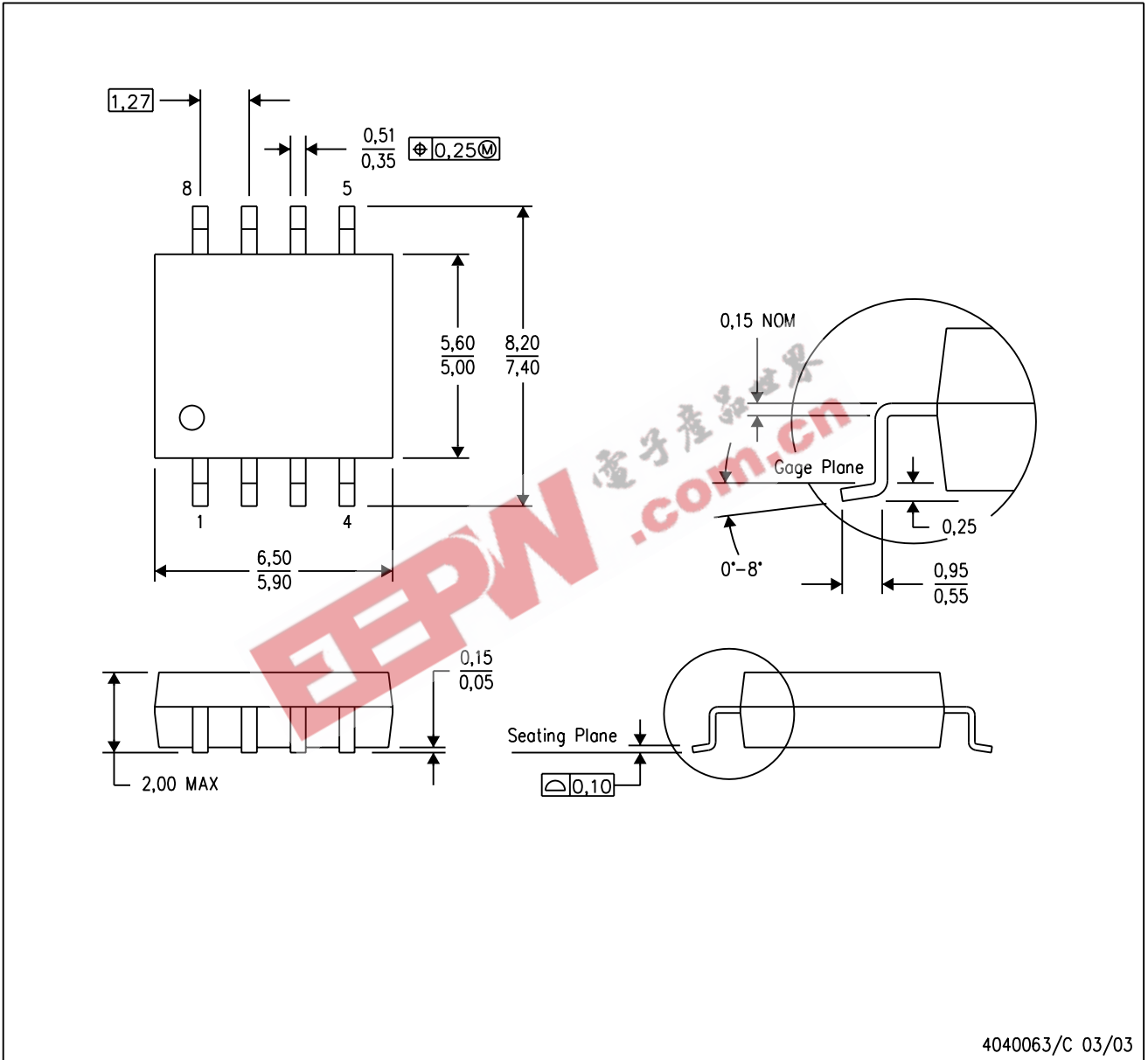


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - △C Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - △D Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AA.

MECHANICAL DATA

PS (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
Low Power Wireless	www.ti.com/lpw	Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments
Post Office Box 655303 Dallas, Texas 75265